

LINEAR TECHNOLOGY MATERIALS DECLARATION

LT6013ISS#PBF

(Engineering Calculation)

SOC

(printed on: 2014-01-19 22:47:50)

TOTAL MASS (g): 0.07283

| COMPONENT MATERIAL | VENDOR/INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL Pkg. | | |
|-----------------------------|----------------------------------|--------------------------------|-------------------------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.001578 | 1000000 | 21666.9394531 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000066 | 1000000 | 906.221862793 | | |
| Lead Frame | A42 | Copper (Cu) | 7440-50-8 | 0.000000 | 0 | 0 | | |
| | | Iron (Fe) | 7439-89-6 | 0.014071 | 580000 | 193203.75 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000000 | 0 | 0 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000000 | 0 | 0 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.010189 | 420000 | 139901.421875 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-96-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead Frame Total: | | | | 0.024260 | 1000000 | 333105.1875 |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.001477 | 1000000 | 20278.1132812 | | |
| | | External Plating Total: | | | | 0.001477 | 1000000 | 20278.1132812 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000194 | 1000000 | 2663.74267578 | | |
| | | Internal Plating Total: | | | | 0.000194 | 1000000 | 2663.74267578 |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.000611 | 750000 | 8416.87890625 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.002094 | 250000 | 2801.04916641 | | |
| | | Die Attach Total: | | | | 0.000817 | 1000000 | 11217.927344 |
| | | Encapsulation | MULTIAROMATIC RESIN BOND FREE | Resin (EP) | | 0.006638 | 150000 | 9143.9453125 |
| Bromine (Br) | 40093-93-8 | | | 0.000000 | 0 | 0 | | |
| Silica (SiO2) | 60676-86-0 | | | 0.036288 | 820000 | 498257.25 | | |
| Antimony Trioxide (Sb2O3) | 1309-64-4 | | | 0.000000 | 0 | 0 | | |
| Metal Hydroxide | | | | 0.001106 | 25000 | 15186.0820312 | | |
| Carbon Black (C) | 1333-86-4 | | | 0.000221 | 5000 | 3034.4699707 | | |
| Encapsulation Total: | | | | | | 0.044253 | 1000000 | 607621.75 |
| Bond Wire Estimated | AFW/TANAKA/Kn | Gold (Au) | 7440-57-5 | 0.000185 | 1000000 | 2540.1672633 | | |

TOTAL MASS (g): 0.072830